CMXD6001

SURFACE MOUNT
TRIPLE ISOLATED
ULTRA LOW LEAKAGE
SILICON SWITCHING DIODES





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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMXD6001 type contains three (3) Isolated Silicon Switching Diodes, manufactured by the epitaxial planar process, epoxy molded in a SUPERmini™ surface mount package, and designed for switching applications requiring extremely low leakage.

MARKING CODE: X01

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Continuous Reverse Voltage	V_{R}	75	V
Peak Repetitive Reverse Voltage	V_{RRM}	100	V
Continuous Forward Current	ΙF	250	mA
Peak Repetitive Forward Current	I _{FRM}	250	mA
Peak Forward Surge Current, tp=1.0µs	I _{FSM}	4.0	Α
Peak Forward Surge Current, tp=1.0s	I _{FSM}	1.0	Α
Power Dissipation	P_{D}	350	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	$\Theta_{\sf JA}$	357	°C/W

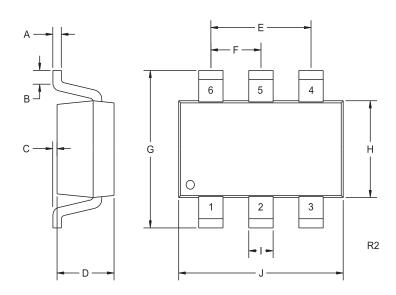
ELECTRICAL CHARACTERISTICS PER DIODE: (T _A =25°C unless otherwise noted)							
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS			
^I R	V _R =75V		500	pA			
BV_R	I _R =100μA	100		V			
V_{F}	I _F =1.0mA		0.85	V			
V_{F}	I _F =10mA		0.95	V			
V_{F}	I _F =100mA		1.1	V			
C _T	V _R =0, f=1.0MHz		2.0	pF			
t _{rr}	$I_R=I_F=10$ mA, $I_{rr}=1.0$ mA, $R_L=100$ Ω		3.0	μs			

CMXD6001

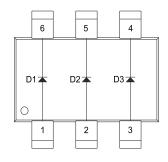
SURFACE MOUNT TRIPLE ISOLATED ULTRA LOW LEAKAGE SILICON SWITCHING DIODES



SOT-26 CASE - MECHANICAL OUTLINE



PIN CONFIGURATION



DIMENSIONS						
	INCHES		MILLIMETERS			
SYMBOL	MIN	MAX	MIN	MAX		
Α	0.004	0.007	0.11	0.19		
В	0.016	-	0.40	-		
С	-	0.004	-	0.10		
D	0.039	0.047	1.00	1.20		
E	0.074	0.075	1.88	1.92		
F	0.037	0.038	0.93	0.97		
G	0.102	0.118	2.60	3.00		
Н	0.059	0.067	1.50	1.70		
	0.016		0.41			
J	0.110	0.118	2.80	3.00		

SOT-26 (REV: R2)

LEAD CODE:

- 1) Anode D1
- 2) Anode D2
- 3) Anode D3
- 4) Cathode D3
- 5) Cathode D2
- 6) Cathode D1

MARKING CODE: X01

R4 (9-May 2011)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp. 145 Adams Avenue Hauppauge, NY 11788 USA

Main Tel: (631) 435-1110 Main Fax: (631) 435-1824

Support Team Fax: (631) 435-3388

www.centralsemi.com

Worldwide Field Representatives: www.centralsemi.com/wwreps

Worldwide Distributors:

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